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Figure 1A

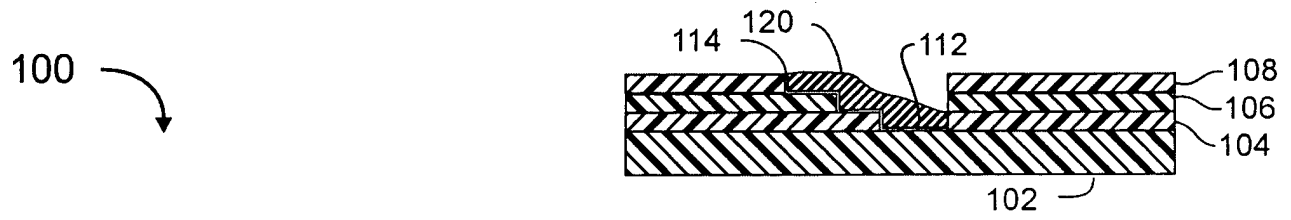


Figure 1B

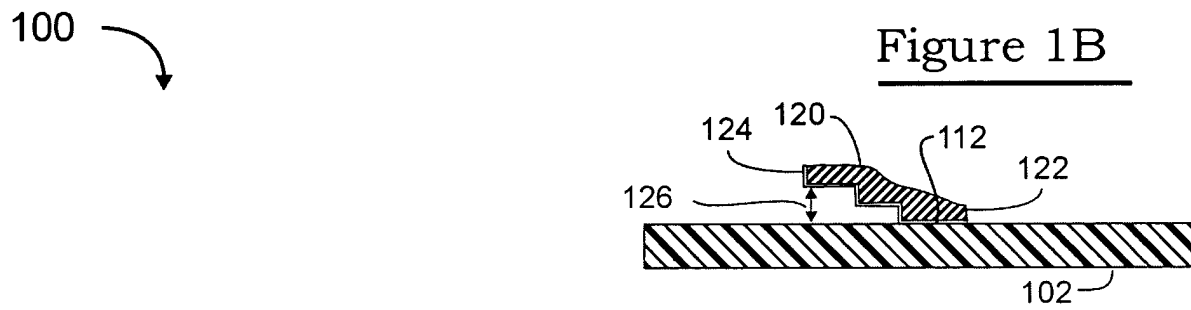
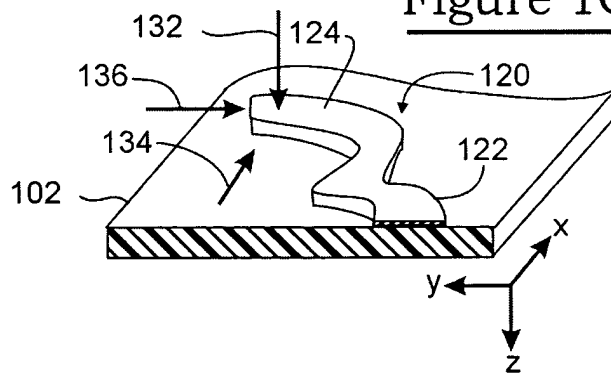
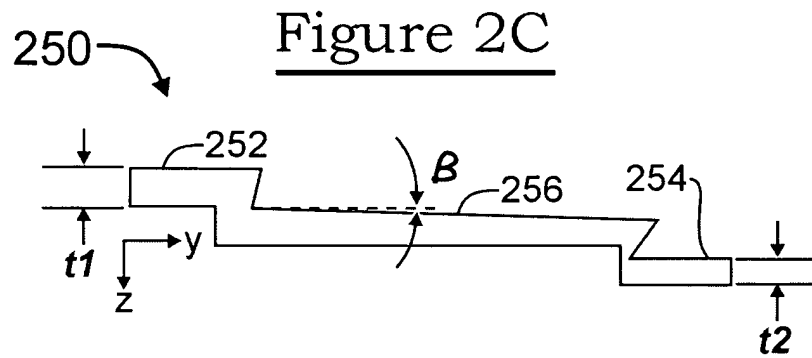
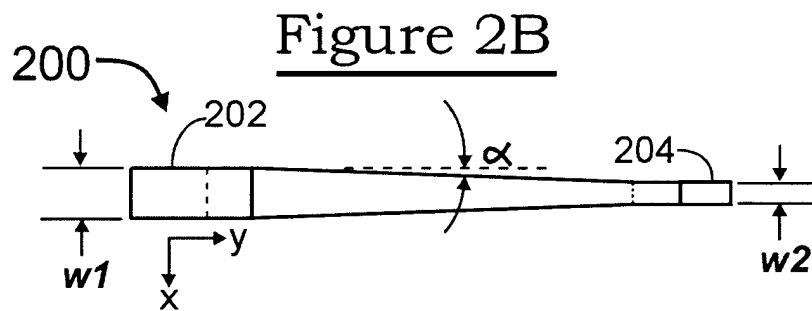
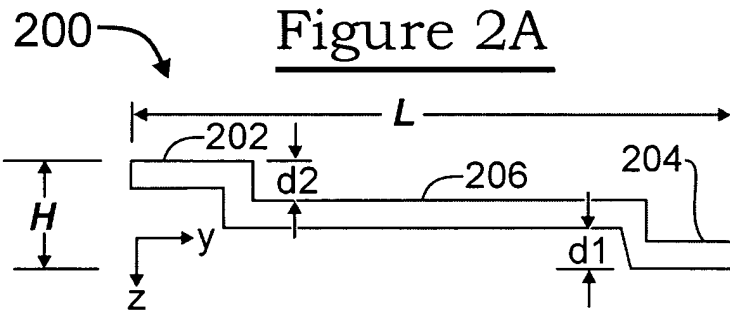


Figure 1C



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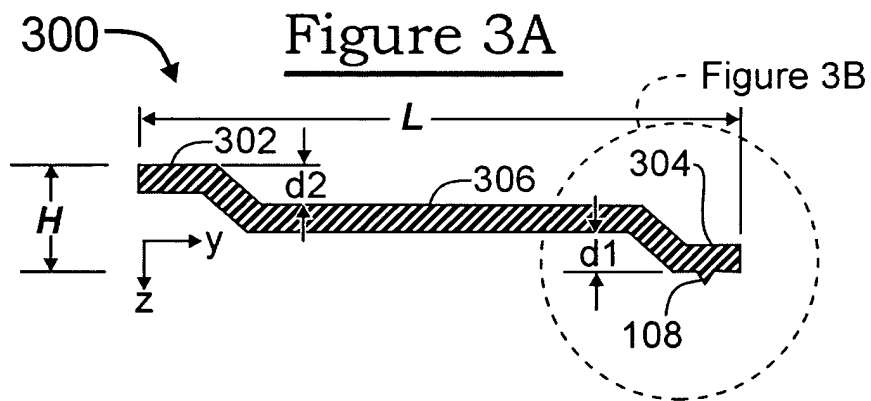


Figure 3B

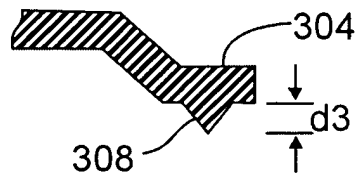
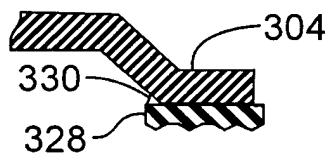


Figure 3C



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Figure 4A

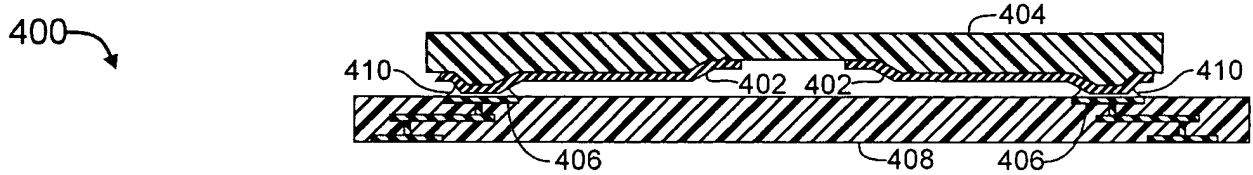


Figure 4B

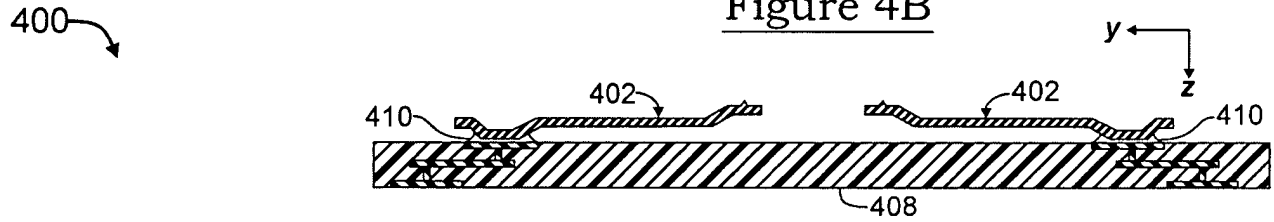
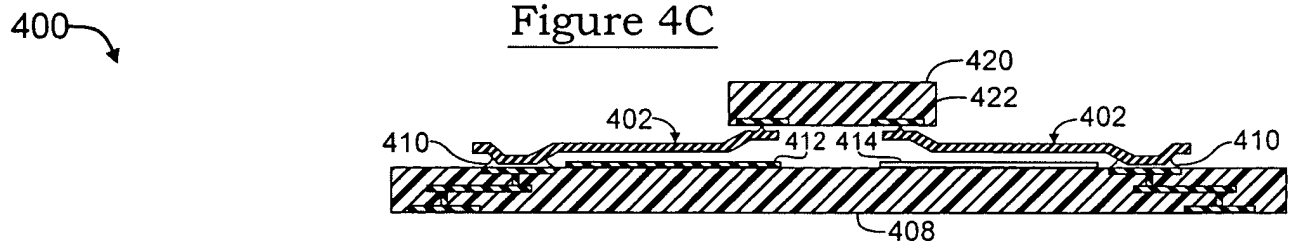


Figure 4C



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Figure 5A

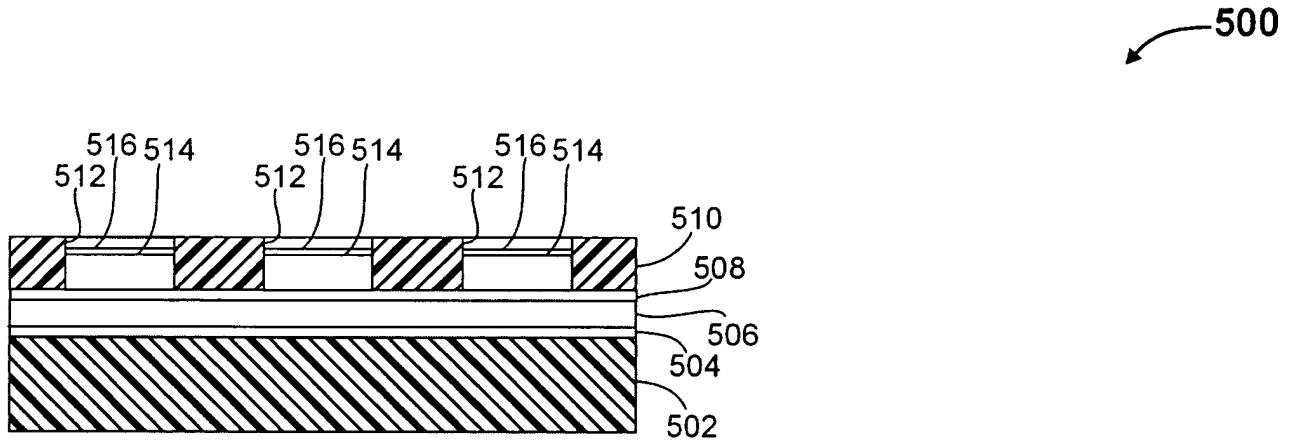
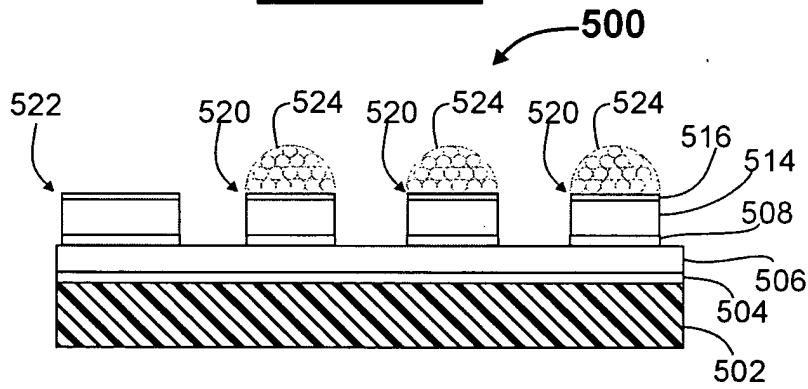


Figure 5B



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Figure 5C

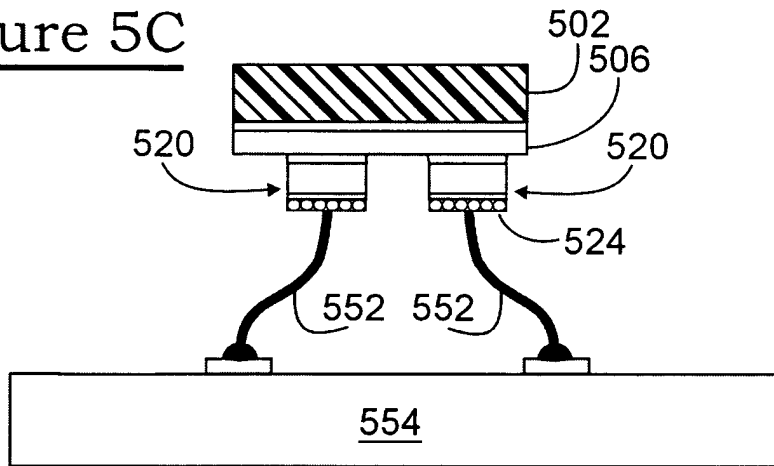
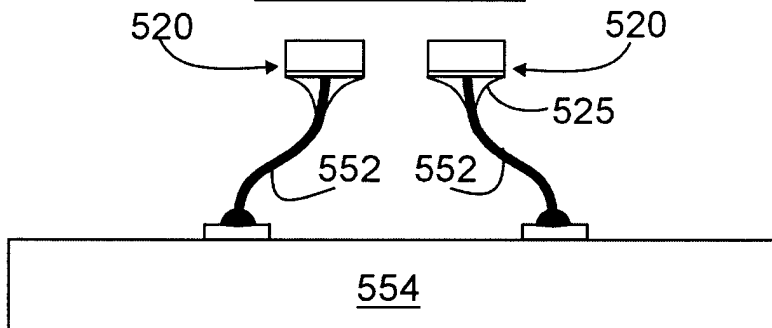
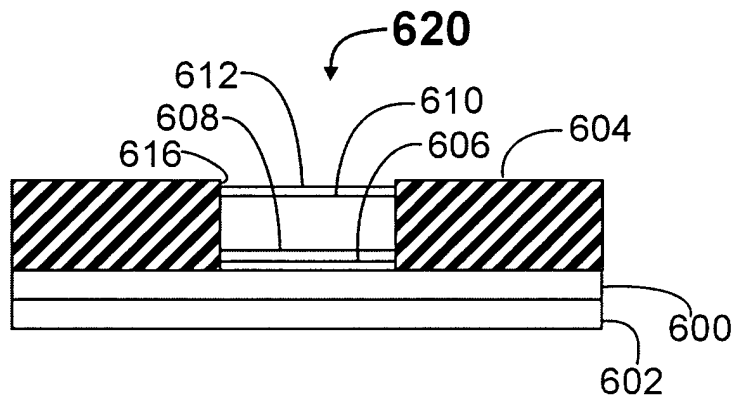


Figure 5D



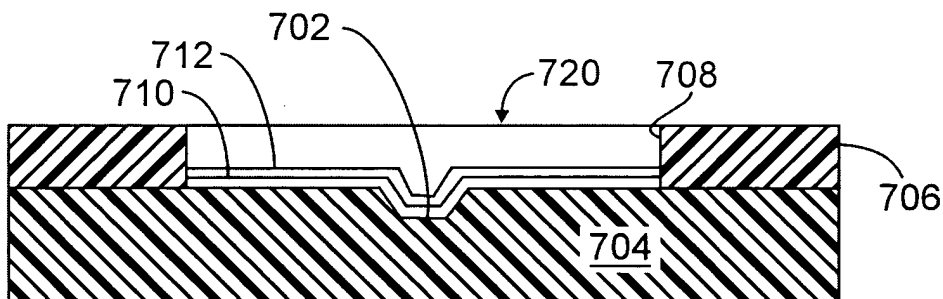
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Figure 6



700

Figure 7



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800

Figure 8A

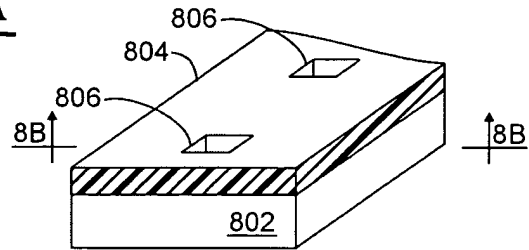


Figure 8B

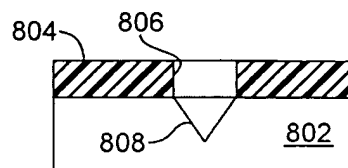


Figure 8C

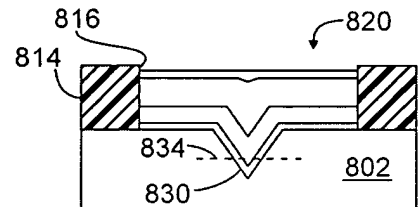


Figure 8D

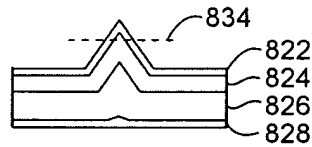


Figure 8E

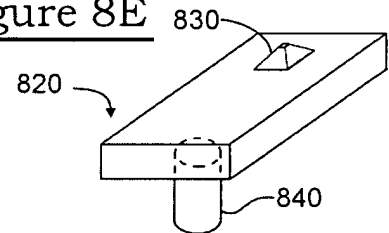
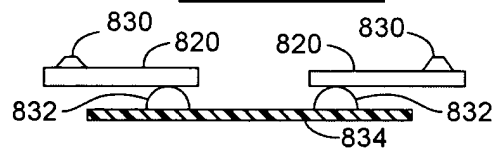


Figure 8F



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Figure 9A

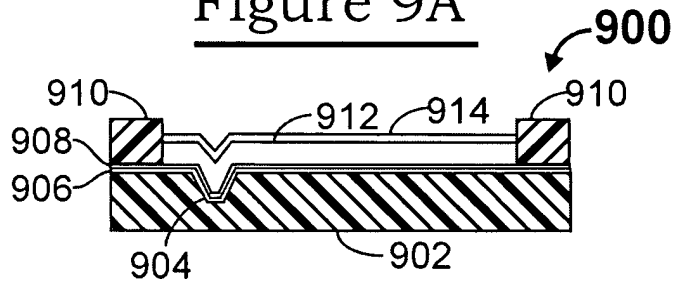


Figure 9B

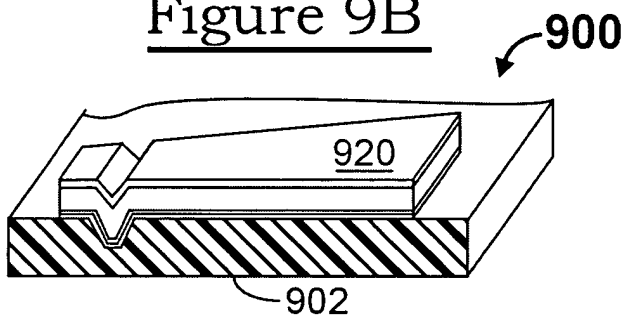


Figure 9C

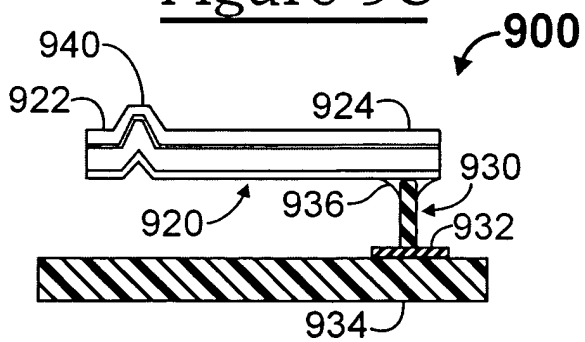


Figure 10B

Figure 10B is a cross-sectional view of a device 1000. The device consists of a substrate 1002, a thin layer 1004, and a patterned layer 1010. The patterned layer 1010 includes features 1012 and 1020.

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Figure 10C

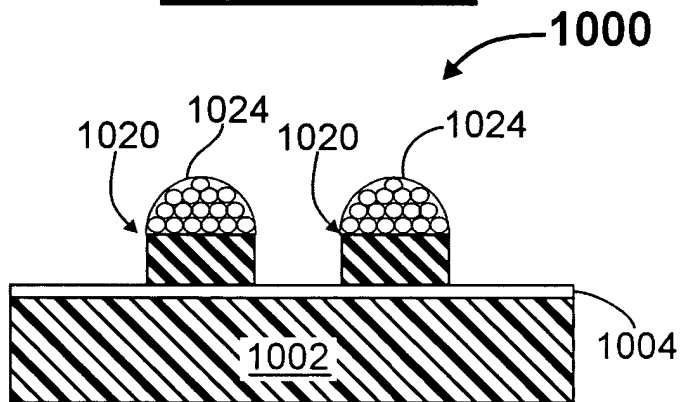


Figure 10D

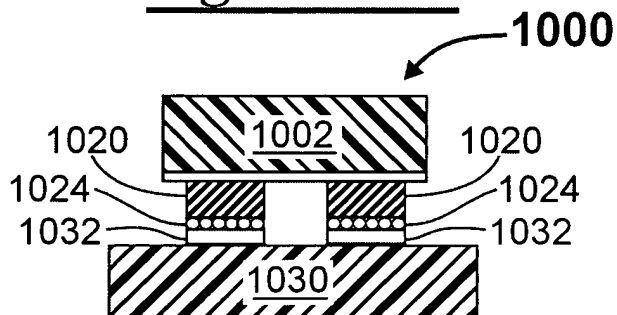
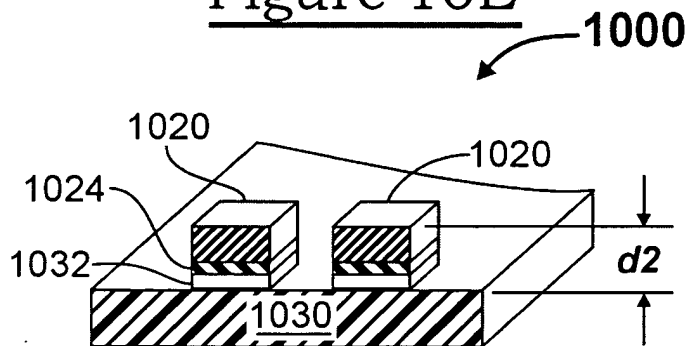


Figure 10E



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Figure 11A

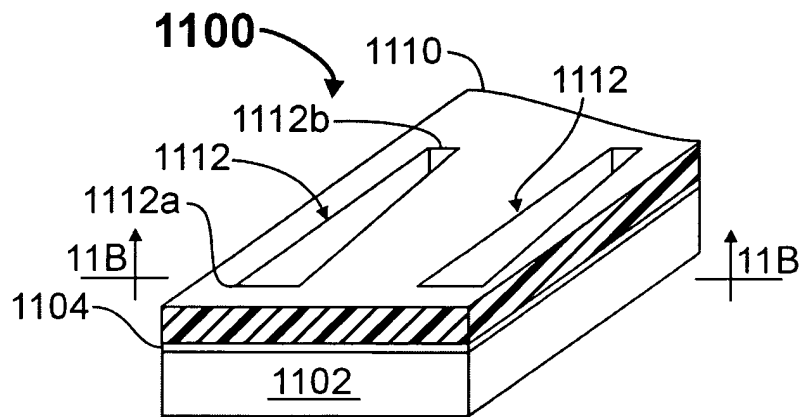
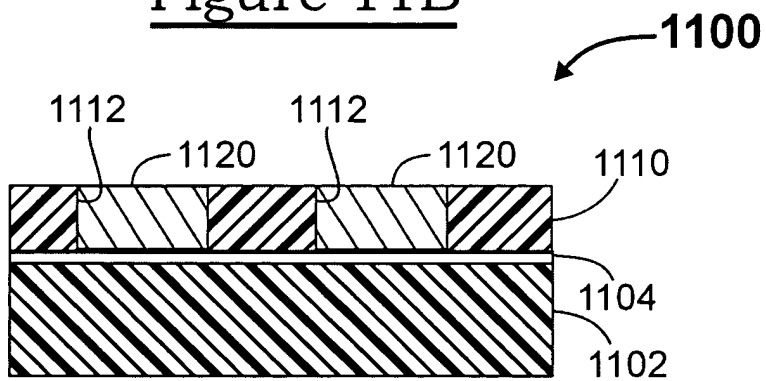


Figure 11B



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Figure 11C

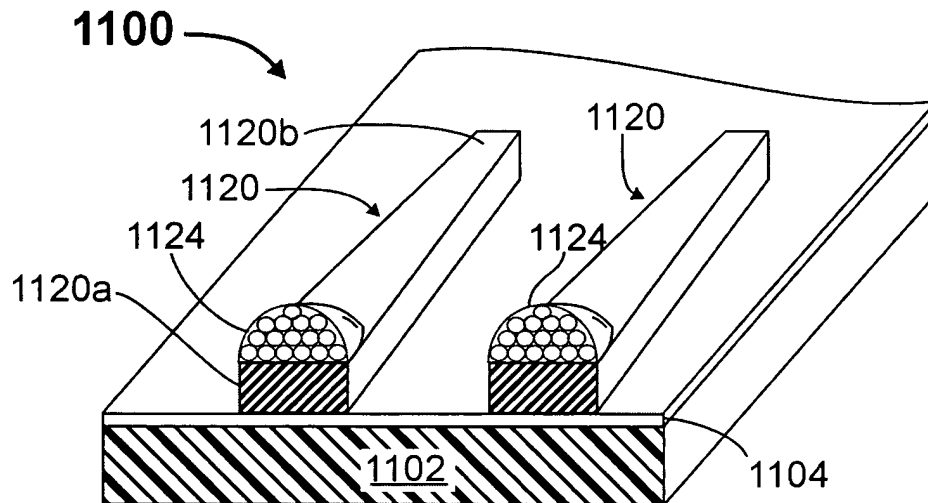


Figure 11D

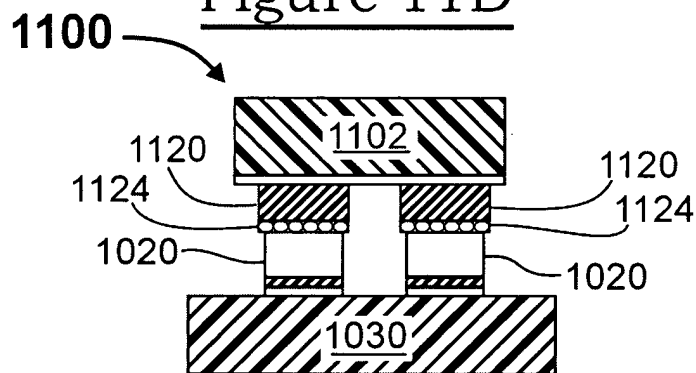
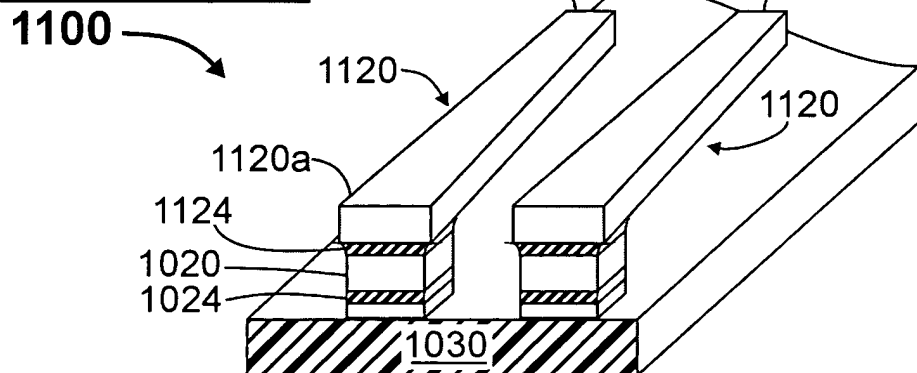


Figure 11E



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Figure 12A

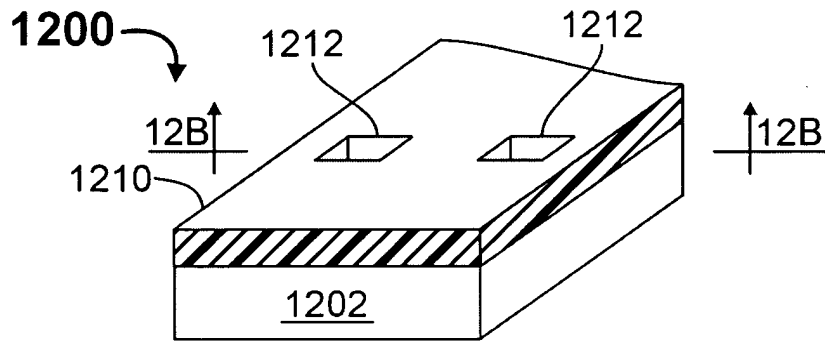


Figure 12B

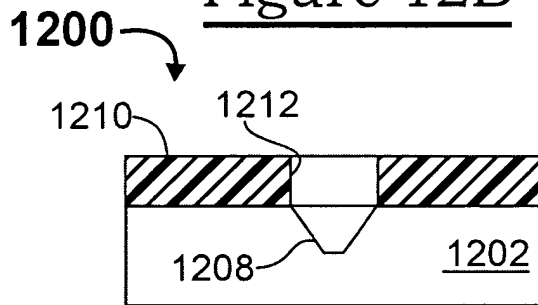
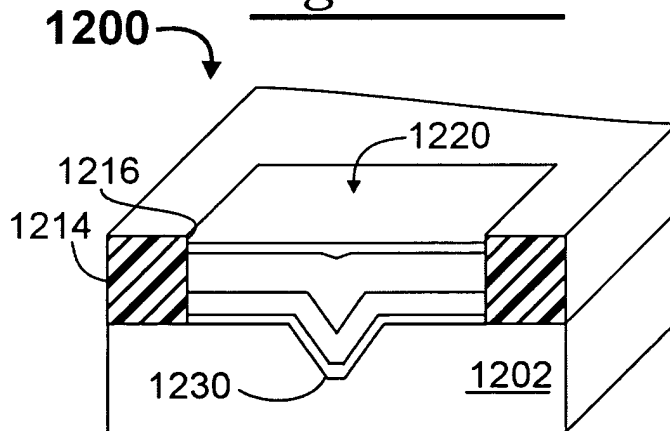


Figure 12C



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Figure 12D

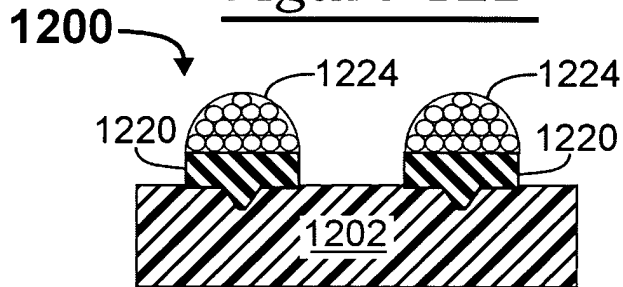


Figure 12E

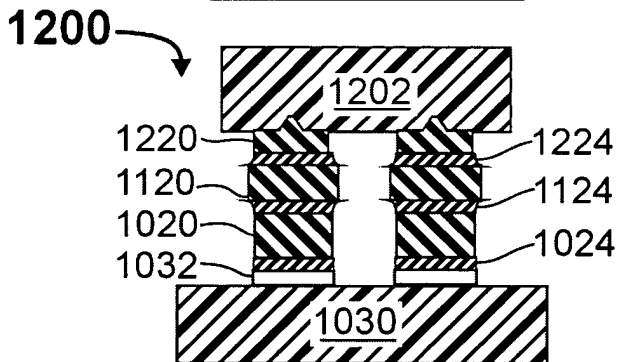


Figure 12F

